

Features

- Halogen Free. "Green" Device (Note 1)
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings @ 25°C Unless Otherwise Specified

- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 250°C/W Junction to Ambient (Note1)

| Parameter | Symbol | Rating | Unit |
|-----------------------------------|-----------|-------------------------|------|
| Collector-Base Voltage | V_{CBO} | 100 | V |
| Collector-Emitter Voltage | V_{CEO} | 80 | V |
| Emitter-Base Voltage | V_{EBO} | 5 | V |
| Collector Current | I_C | 1.0 | A |
| Base Current | I_B | 0.1 | A |
| Peak Base Current ($t_p < 1ms$) | I_{BM} | 0.2 | A |
| Collector Power Dissipation | P_C | 0.50 ^(Note2) | W |
| | | 0.95 ^(Note3) | |
| | | 1.35 ^(Note4) | |

Classification Of $h_{FE(1)}$

| Rank | BCX56 | BCX56-10 | BCX56-16 |
|----------------------|--------|----------|----------|
| Range of $h_{FE(1)}$ | 63-250 | 63-160 | 100-250 |
| Marking | BH | BK | BL |

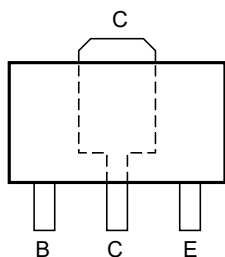
Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Note:2. Device mounted on an FR4 PCB, Single-sided copper, tin-plated and standard footprint.

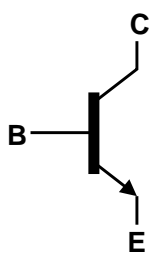
Note:3. Device mounted on an FR4 PCB, Single-sided copper, mounting pad for collector 1cm²

Note:4. Device mounted on an FR4 PCB, Single-sided copper, mounting pad for collector 6cm²

Pin Configuration - Top View

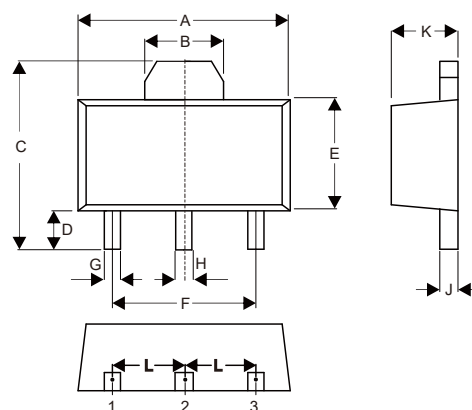


Internal Structure



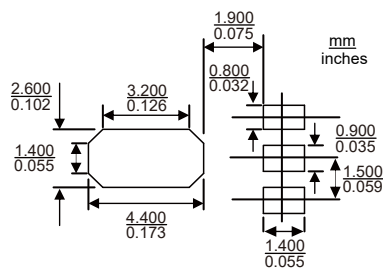
NPN Plastic Encapsulate Transistors

SOT-89



| DIM | DIMENSIONS | | | | NOTE |
|-----|------------|-------|------|------|------|
| | INCHES | | MM | | |
| | MIN | MAX | MIN | MAX | |
| A | 0.169 | 0.185 | 4.30 | 4.70 | |
| B | 0.061 | | 1.55 | | TYP. |
| C | 0.154 | 0.171 | 3.91 | 4.35 | |
| D | 0.031 | 0.047 | 0.80 | 1.20 | |
| E | 0.089 | 0.104 | 2.25 | 2.65 | |
| F | 0.118 | | 3.00 | | TYP. |
| G | 0.013 | 0.020 | 0.33 | 0.52 | |
| H | 0.015 | 0.021 | 0.38 | 0.53 | |
| J | 0.014 | 0.017 | 0.35 | 0.44 | |
| K | 0.055 | 0.063 | 1.40 | 1.60 | |
| L | 0.059 | | 1.50 | | TYP. |

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C Unless Otherwise Specified

| Parameter | Symbol | Min | Typ | Max | Units | Conditions |
|--------------------------------------|---------------|-----|-----|-----|---------|-----------------------------------|
| Collector-Base Breakdown Voltage | $V_{(BR)CBO}$ | 100 | | | V | $I_C=100\mu A, I_E=0$ |
| Collector-Emitter Breakdown Voltage | $V_{(BR)CEO}$ | 80 | | | V | $I_C=10mA, I_B=0$ |
| Emitter-Base Breakdown Voltage | $V_{(BR)EBO}$ | 5 | | | V | $I_E=10\mu A, I_C=0$ |
| Collector-Base Cutoff Current | I_{CBO} | | | 0.1 | μA | $V_{CB}=30V, I_E=0$ |
| Emitter-Base Cutoff Current | I_{EBO} | | | 0.1 | μA | $V_{EB}=5.0V, I_C=0$ |
| DC Current Gain | $h_{FE(1)}$ | 63 | | 250 | | $V_{CE}=2.0V, I_C=150mA$ |
| | $h_{FE(2)}$ | 40 | | | | $V_{CE}=2.0V, I_C=5mA$ |
| | $h_{FE(3)}$ | 25 | | | | $V_{CE}=2.0V, I_C=500mA$ |
| Collector-Emitter Saturation Voltage | $V_{CE(sat)}$ | | | 0.5 | V | $I_C=500mA, I_B=50mA$ |
| Base-Emitter Voltage | V_{BE} | | | 1.0 | V | $V_{CE}=2.0V, I_C=500mA$ |
| Transition Frequency | f_T | | 130 | | MHz | $V_{CE}=5.0V, I_C=10mA, f=100MHz$ |

Curve Characteristics

Fig. 1 - Static Characteristics

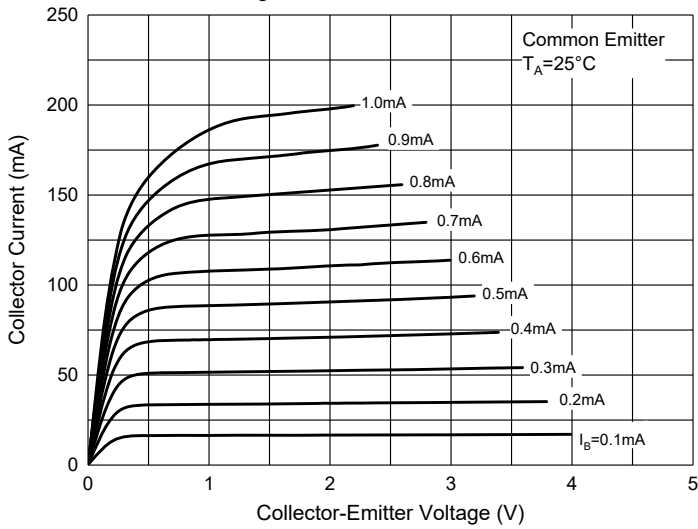


Fig. 2 - DC Current Gain Characteristics

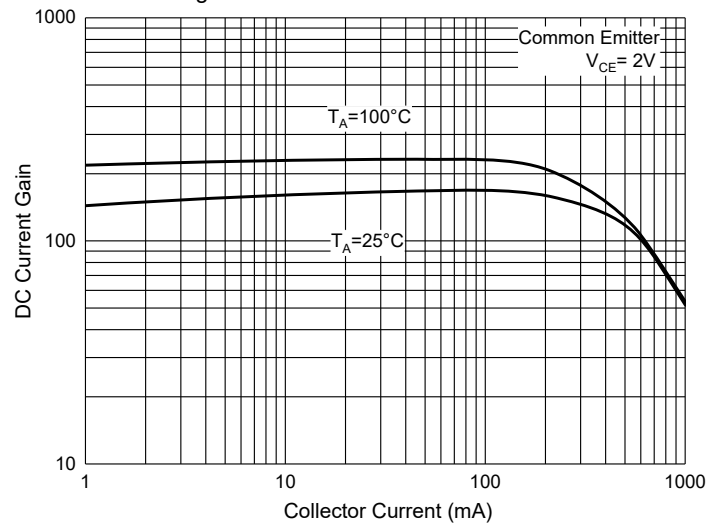


Fig. 3 - Collector-Emitter Saturation Voltage Characteristics

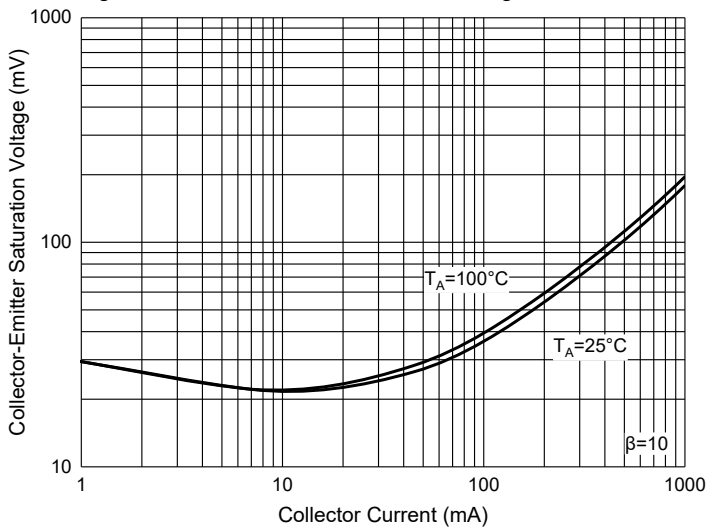


Fig. 4 - Base-Emitter Saturation Voltage Characteristics

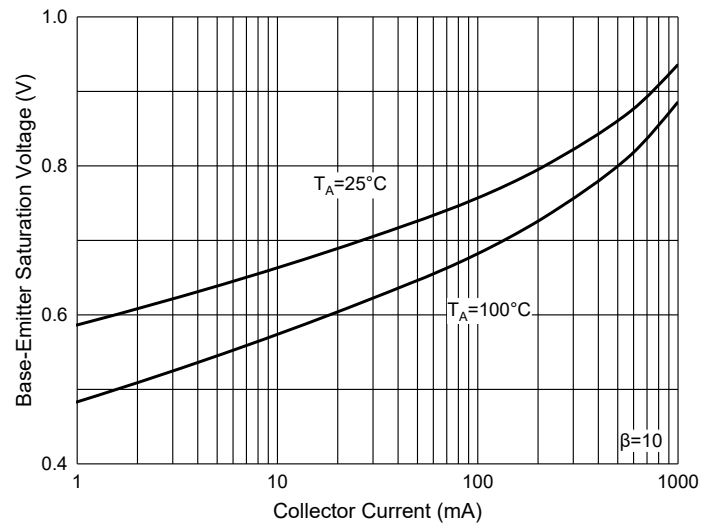


Fig. 5 - Base-Emitter Voltage Characteristics

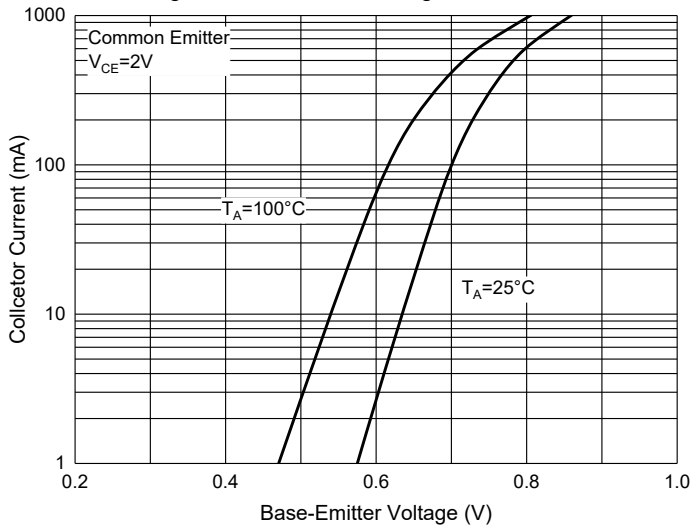


Fig. 6 - Power Derating Curve

